

THE UNITED STATES PATENT AND TRADEMARK OFFICE

**REVOCATION AND NEW POWER OF ATTORNEY AND  
CHANGE OF CORRESPONDENCE ADDRESS**

I, *Dr. Graham Fisher, Director of Intellectual Property of MEMC Electronic Materials, Inc.*, the Assignee of the entire right, title, and interest in the *U.S. Patent Application(s) and/or Patent(s) identified on the attached Schedule A*, hereby revoke all previous powers of attorney or authorizations of agent given and do hereby appoint the attorneys or agents associated with the following Customer Number, with full power of substitution and revocation, to prosecute and transact all business in the Patent and Trademark Office connected therewith for the *U.S. Patent Application(s) and/or Patent(s) listed in the attached Schedule A*:

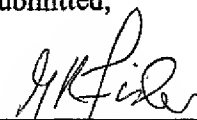
*Customer Number: 76681*

Please direct all correspondence in connection with said *U.S. Patent Application(s) and/or Patent(s)* to:

*Customer Number: 76681*

Respectfully submitted,

Date: 5/13/2008

  
\_\_\_\_\_  
Dr. Graham Fisher  
Director of Intellectual Property  
MEMC Electronic Materials, Inc.

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

STATEMENT UNDER 37 CFR 3.73(b)

**MEMC Electronic Materials, Inc.**, a Delaware Corporation, pursuant to 37 CFR 3.73(b), hereby states that it is the Assignee of the entire right, title, and interest in *U.S. Patent Application(s) and/or Patent(s) on the attached Schedule A.*

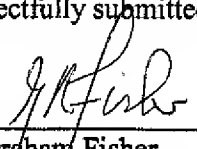
The entire rights, title, and interest in the aforementioned Patent Application(s) and/or Patent(s) were conveyed to **MEMC Electronic Materials, Inc.** via Assignment(s) recorded with the United States Patent and Trademark Office at the *Reel/Frame Numbers on the attached Schedule A.*

The undersigned, **Dr. Graham Fisher, Director of Intellectual Property**, has full authorization to act on behalf of Assignee **MEMC Electronic Materials, Inc.**

Respectfully submitted,

Date: \_\_\_\_\_

5/13/2008

  
\_\_\_\_\_  
Dr. Graham Fisher  
Director of Intellectual Property  
MEMC Electronic Materials, Inc.

# APPENDIX A

## Owned by MEMC Electronic Materials, Inc.

| ATTORNEY REFERENCE       | CONF. NO | PUBLICATION NO. & DATE        | SERIAL NO. FILING DATE | PATENT NO. ISSUE DATE | CURRENT OWNER/ ASSIGNEE         | REEL AND FRAME NO.   | TITLE  |
|--------------------------|----------|-------------------------------|------------------------|-----------------------|---------------------------------|--|--|
| 28744-177 (MEMC3114.1)   | 4497     | US 2007-0045738-A1 3/1/07     | 11/461,956 8/2/2006    |                       | MEMC Electronic Materials, Inc. | 018400/0468  | METHOD FOR THE MANUFACTURE OF A STRAINED SILICON-ON-INSULATOR STRUCTURE  |
| 28744-60 (MEMC3115.1)    | 3973     | US 2007-0042566-A1 2/2/2007   | 11/461,853 8/1/2006    |                       | MEMC Electronic Materials, Inc. | 018486/0347  | STRAINED SILICON ON INSULATOR (SSOI) STRUCTURE WITH IMPROVED CRYSTALLINITY IN THE STRAINED SILICON LAYER   |
| 28744-155 (MEMC3116)     | 5718     | US 2006-0231035-A1 10/19/2006 | 11/107,444 4/15/2005   |                       | MEMC Electronic Materials, Inc. | 016278/0974  | MODIFIED SUSCEPTOR FOR BARREL REACTOR  |
| 28744-346 (MEMC3126)     | 9475     | US 2007-0249136-A1 10/25/2007 | 11/408,503 4/21/2006   |                       | MEMC Electronic Materials, Inc. | 017974/0835  | SILICON STRUCTURES WITH IMPROVED RESISTANCE TO RADIATION EVENTS  |
| 28744-347 (MEMC3127.1)   | 4131     | US 2007-0179659-A1 8/2/2007   | 11/617,430 12/28/2006  |                       | MEMC Electronic Materials, Inc. | 019136/0568  | DOUBLE SIDE WAFER GRINDER AND METHODS FOR ASSESSING WORKPIECE NANOTOPOLOGY   |
| 28744-349 (MEMC3128.1)   | 5925     | US 2007-0176238-A1 8/12/2007  | 11/698,728 1/26/2007   |                       | MEMC Electronic Materials, Inc. | 019110/0543  | SILICON WAFER WITH HIGH THERMAL CONDUCTIVITY   |
| 28744-351 (MEMC3131.1)   | 2048     | US 2007-0178807-A1 8/12/2007  | 11/621,920 1/10/2007   |                       | MEMC Electronic Materials, Inc. | 019177/0655  | WIRE SAW INGOT SLICING SYSTEM AND METHOD WITH INGOT PREHEATING, WEB PREHEATING, SLURRY TEMPERATURE CONTROL AND/OR SLURRY FLOW RATE CONTROL         |
| MEMC3139                 | 2638     |                               | 11/616,485 12/27/2006  |                       | MEMC Electronic Materials, Inc. | 019686/0657  | WAFER SUPPORT AND METHOD OF MAKING WAFER SUPPORT   |
| 28744-63 (MEMC3151)      | 2685     | US 2007-0117350-A1 5/24/2007  | 11/616,517 12/27/2006  |                       | MEMC Electronic Materials, Inc. | 018823/0530  | STRAINED SILICON ON INSULATOR (SSOI) WITH LAYER TRANSFER FROM OXIDIZED DONOR   |
| 28744-147 (MEMC3152)     | 8867     |                               | 11/614,129 12/21/2006  |                       | MEMC Electronic Materials, Inc. | 019935/0398  | METHOD OF POLISHING A SEMICONDUCTOR WAFER  |
| 28744-354 (MEMC3155)     | 4137     | US 2007-0179660-A1 8/12/2007  | 11/617,433 12/28/2006  |                       | MEMC Electronic Materials, Inc. | 019136/0619  | DOUBLE SIDE WAFER GRINDER AND METHODS FOR ASSESSING WORKPIECE NANOTOPOLOGY   |
| 28744-170 (MEMC972703.1) | 5307     | US 2007-0224783-A1 9/27/2007  | 11/753,294 5/24/2007   |                       | MEMC Electronic Materials, Inc. | Continuation of 11/058,996 recorded at 9409/0291   | PROCESS FOR FORMING LOW DEFECT DENSITY, IDEAL OXYGEN PRECIPITATING SILICON   |
| 28744-356 (MEMC980411.1) | 2920     | US 2007-0238266-A1 10/11/2007 | 11/763,043 6/14/2007   |                       | MEMC Electronic Materials, Inc. | Division of 10/911,965 recorded at 010225/0266   | NON-UNIFORM MINORITY CARRIER LIFETIME DISTRIBUTIONS IN HIGH PERFORMANCE SILICON POWER DEVICES  |
| 28744-357 (MEMC983053.1) | 8402     | US 2008-0020168-A1 1/24/2008  | 11/833,730 8/3/2007    |                       | MEMC Electronic Materials, Inc. | Continuation of 10/963,137 which is a continuation of 10/038,084 recorded at 010449/0840     | SILICON ON INSULATOR STRUCTURE WITH A SINGLE CRYSTAL CZ SILICON DEVICE LAYER HAVING A REGION WHICH IS FREE OF AGGLOMERATED INTRINSIC POINT DEFECTS |
| 28744-340 (MEMC3094.8)   | 1290     | US 2008-0020684-A1 1/24/2008  | 10/598,851 5/10/2007   |                       | MEMC Electronic Materials, Inc. | U.S. National of PCT based on provisional 60/554,684 recorded at 015315/0827 and 015263/0403 | WAFER CLAMPING DEVICE FOR A DOUBLE SIDE GRINDER  |